

**NEC**

MOS Field Effect Power Transistor

**NP24N06HLB, NP24N06ILB**

SWITCHING  
N-CHANNEL POWER MOS FET  
INDUSTRIAL USE

**DESCRIPTION**

This product is N-Channel MOS Field Effect Transistor designed for high current switching applications.

**FEATURES**

- Channel temperature 175 degree rated
- Super Low On-State Resistance  
 $R_{DS(on)1} = 70m\Omega$  Max. ( $V_{GS} = 10V, I_D = 12A$ )  
 $R_{DS(on)2} = 90m\Omega$  Max. ( $V_{GS} = 5V, I_D = 5A$ )
- Low  $C_{iss}$   $C_{iss} = 860pF$  Typ.
- Built-in Gate Protection Diode

**ORDERING INFORMATION**

PART NUMBER	PACKAGE
NP24N06HLB	TO-251
NP24N06ILB	TO-252

**ABSOLUTE MAXIMUM RATINGS(Ta=25°C)**

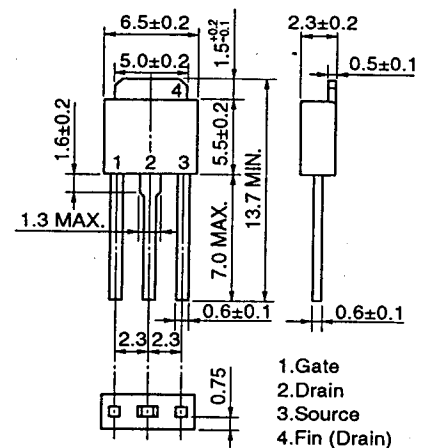
Drain to Source Voltage	$V_{DSS}$	60	V
Gate to Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current(DC)	$I_{D(DC)}$	$\pm 24$	A
Drain Current(pulse)*	$I_{D(pulse)}$	$\pm 40$	A
Total Power Dissipation(Ta=25°C)	$P_T$	1.2	W
Total Power Dissipation(Tch=25°C)	$P_T$	51	W
Single Avalanche Current	$I_{AS}$	24	A
Single Avalanche Energy	$E_{AS}$	T.B.D.	mJ
Channel Temperature	$T_{ch}$	175	°C
Storage Temperature	$T_{stg}$	- 55 ~ + 175	°C

\*  $PW \leq 10\mu s, Duty\ Cycle \leq 1\%$ \*\*Starting  $T_{ch} = 25^\circ C, R_G = 25\Omega, T_{GS} 20V \rightarrow 0$ **THERMAL RESISTANCE**

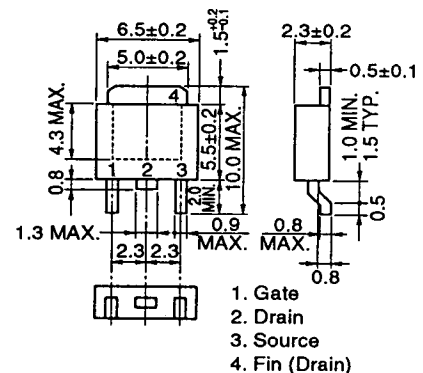
Channel to Case	$R_{th(ch-c)}$	2.94	°C/W
Channel to Ambient	$R_{th(ch-a)}$	125	°C/W

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device acutally used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

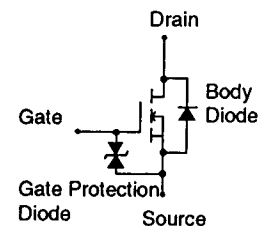
This information in this document is being issued in advance of the production cycle for the device. The parameter for the device may change before final production or NEC Corporation, at its own discretion, may withdraw the device prior to its production.

**PACKAGE DIMENSIONS**  
(in millimeter)

TO-251 (MP-3)



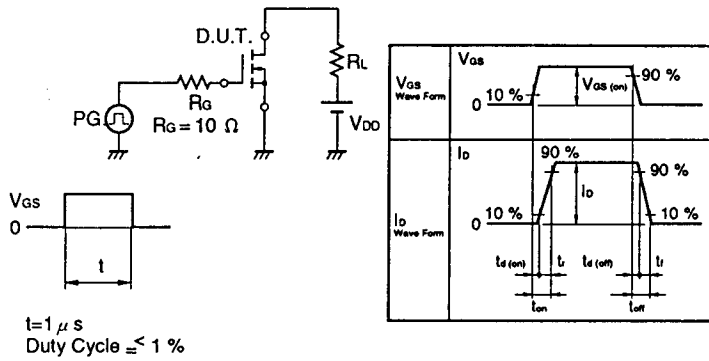
TO-252 (MP-3Z)



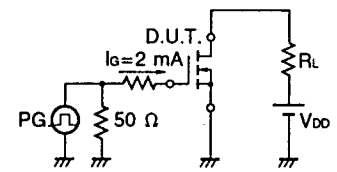
ELECTRICAL CHARACTERISTICS(Ta=25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	$V_{GS}=10V, I_D=12A$		52	70	mΩ
	$R_{DS(on)2}$	$V_{GS}=5V, I_D=5A$		63	90	mΩ
	$R_{DS(on)3}$	$V_{GS}=4V, I_D=5A$		68	95	mΩ
Gate to Source Cutoff Voltage	$V_{GS(off)}$	$V_{DS}=10V, I_D=1mA$	1.0	1.6	2.0	V
Forward Transfer Admittance	$ y_{fs} $	$V_{DS}=10V, I_D=5A$	7.0	12		S
Drain Leakage Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0$			10	μA
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0$			±10	μA
Input Capacitance	$C_{iss}$	$V_{DS}=10V$		860	1900	pF
Output Capacitance	$C_{oss}$	$V_{GS}=0$		440	660	pF
Reverse Transfer Capacitance	$C_{rss}$	$f=1MHz$		110	200	pF
Turn-On Delay Time	$t_{d(on)}$	$I_D=5A$		15	33	nS
Rise Time	$t_r$	$V_{GS(on)}=10V$		90	230	nS
Turn-Off Delay Time	$t_{d(off)}$	$V_{DD}=30V$		75	150	nS
Fall Time	$t_f$	$R_G=10\Omega$		35	90	nS
Total Gate Charge	$Q_G$	$I_D=10A$		24	36	nC
Gate to Source Charge	$Q_{GS}$	$V_{DD}=48V$		2.6		nC
Gate to Drain Charge	$Q_{GD}$	$V_{GS}=10V$		6.0		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	$I_F=10A, V_{GS}=0$		1.0		V
Reverse Recovery Time	$t_{rr}$	$I_F=10A, V_{GS}=0$		85		ns
Reverse Recovery Charge	$Q_{rr}$	$di/dt=50A/\mu s$		220		nC

Test Circuit 1 Switching Time



Test Circuit 2 Gate Charge



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Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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Anti-radioactive design is not implemented in this product.